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September 2012

74AUP1G59 TinyLogic[®] Low Power Universal Configurable Two-Input Logic Gate (Open Drain Output)

Features

- 0.8V to 3.6V V_{CC} Supply Operation
- 3.6V Over-Voltage Tolerant I/Os at V_{CC} from 0.8V to 3.6V
- Extremely High Speed tpd
 - 3.2ns: Typical at 3.3V
- Power-Off High-Impedance Inputs and Outputs
- Low Static Power Consumption
 - I_{CC}=0.9µA Maximum
- Low Dynamic Power Consumption
 - C_{PD}=3.0pF Typical at 3.3V
- Ultra-Small MicroPak[™] Package

Description

The 74AUP1G59 is a universal, configurable, two-input logic gate with an open drain that provides a high-performance and low-power solution for battery-powered portable applications. This product is designed for a wide low voltage operating range (0.8 V to 3.6 V) and guarantees very low static and dynamic power consumption across the entire voltage range. All inputs are implemented with hysteresis to allow for slower transition input signals and better switching noise immunity.

The 74AUP1G59 provides for multiple functions, as determined by various configurations of the three inputs. The potential logic functions provided are AND, NAND, OR, NOR, XNOR, inverter, and buffer (see Figure 2 through Figure 8).

Ordering Information

Part Number	Top Mark	Package	Packing Method
74AUP1G59L6X	AL	6-Lead, MicroPak™, 1.0 mm Wide	5000 Units on Tape & Reel
74AUP1G59FHX	AL	6-Lead, MicroPak2™, 1x1 mm Body, .35 mm Pitch	5000 Units on Tape & Reel

Pin Configurations

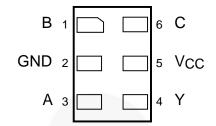


Figure 1. MicroPak™ (Top Through View)

Pin Definitions

Pin#	Name	Description
1	В	Data Input
2	GND	Ground
3	A	Data Input
4	Υ	Output (Open Drain)
5	V _{cc}	Supply Voltage
6	С	Data Input

Function Table

Inputs			Y=Output
С	В	Α	
L	L	L	L
L	L	Н	H ⁽¹⁾
L	Н	L	L
L	Н	Н	H ⁽¹⁾
Н	L	L	H ⁽¹⁾
Н	L	Н	H ⁽¹⁾
Н	Н	L	L
Н	Н	Н	L

H = HIGH Logic Level

L = LOW Logic Level

Note:

1. High impedance output state, open drain.

Function Selection Table

2-Input Logic Function	Connection Configuration
2-Input AND with Inverted Input	Figure 3, Figure 4
2-Input NAND	Figure 2
2-Input NAND with Both Inputs Inverted	Figure 5
2-Input OR	Figure 5
2-Input OR Both Inputs Inverted	Figure 2
2-Input NOR with Inverted Input	Figure 3, Figure 4
2-Input XNOR	Figure 6
Inverter	Figure 7
Buffer	Figure 8

Logic Configurations

Figure 2 through Figure 8 show the logical functions that can be implemented using the 74AUP1G59. The diagrams show the DeMorgan's equivalent logic duals for a given two-input function. The logical

implementation is next to the board-level physical implementation of how the pins should be connected.

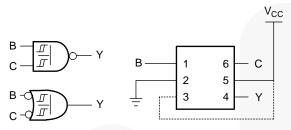


Figure 2. 2-Input NAND Gate or 2-Input OR with Both Inputs Inverted

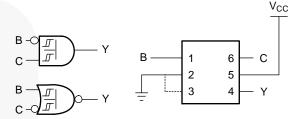


Figure 3. 2-Input AND with Inverted B Input or 2-Input NOR Gate with Inverted C Input

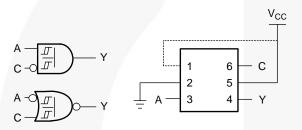


Figure 4. 2-Input AND with Inverted C Input or 2-Input NOR Gate with Inverted A Input

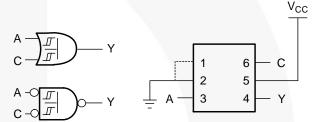


Figure 5. 2-Input OR Gate or 2-Input NAND Gate with Both Inputs Inverted

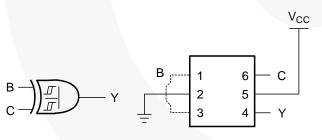


Figure 6. 2-Input XOR Gate

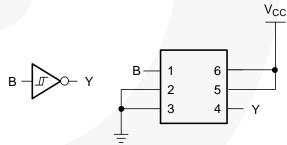


Figure 7. Inverter

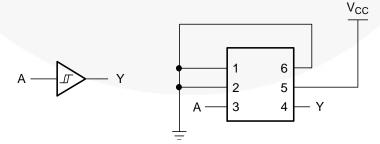


Figure 8. Buffer

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Para	Min.	Max.	Unit	
V _{CC}	Supply Voltage		-0.5	4.6	V
V _{IN}	DC Input Voltage		-0.5	4.6	V
V _{OUT} ⁽²⁾	DC Output Voltage		-0.5	4.6	V
I _{IK}	DC Input Diode Current	V _{IN} < 0V		-50	mA
I _{OK}	DC Output Diode Current	V _{OUT} < 0V		-50	mA
I _{OL}	DC Output Sink Current		+50	mA	
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per	Supply Pin		±50	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature Under Bi	as		+150	°C
T _L	Junction Lead Temperature, Sc	oldering 10s		+260	°C
P_D	Power Dissipation at +85°C	MicroPak™-6		130	mW
. 0	1 ower Bloompation at 100 C	MicroPak2™-6		120	11177
ESD	Human Body Model, JEDEC:JE	SD22-A114		5000	V
LGD	Charged Device Model, JEDEC	:JESD22-C101		2000	V

Note:

Recommended Operating Conditions⁽³⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Condition	Min.	Max.	Unit	
V_{CC}	Supply Voltage		0.8	3.6	V	
V_{IN}	Input Voltage		0	3.6	V	
V _{OUT}	Output Voltage		0	3.6	V	
		V _{CC} =3.0V to 3.6V		4.0		
	Output Current	V _{CC} =2.3V to 2.7V		3.1		
		V _{CC} =1.65V to 1.95V		1.9	mA	
I _{OL}	Output Current	V _{CC} =1.4V to 1.6V		1.7	≤ 1	
		V _{CC} =1.1V to 1.3V		1.1		
		V _{CC} =0.8V		20.0	μA	
T _A	Operating Temperature, Free Air		-40	+85	°C	
θ_{JA}	Thermal Resistance	MicroPak™-6		500	°C/W	
UJA	THOMAI RESISTANCE	MicroPak2™-6		560	- 0///	

Note:

^{2.} In absolute maximum rating must be observed.

^{3.} Unused inputs must be held HIGH or LOW. They may not float.

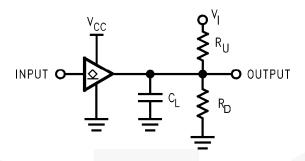
DC Electrical Characteristics

Sumba!	Doromoto-	V	Condition	Condition T _A =2		T _A =-40 to 85°C		Unit
Symbol	Parameter	V _{cc}	Condition	Min.	Max.	Min.	Max.	Unit
		0.80		0.30	0.60	0.30	0.60	
		1.10		0.53	0.90	0.53	0.90	
	Positive	1.40		0.74	1.11	0.74	1.11	.,
V_P	Threshold Voltage	1.65		0.91	1.29	0.91	1.29	V
	- chaige	2.30		1.37	1.77	1.37	1.77	
		3.00		1.88	2.29	1.88	2.29	
		0.80		0.10	0.60	0.10	0.60	
		1.10		0.26	0.65	0.26	0.65	
	Negative	1.40		0.39	0.75	0.39	0.75	.,
V_N	Threshold Voltage	1.65		0.47	0.84	0.47	0.84	V
	, chage	2.30		0.69	1.04	0.69	1.04	
		3.00		0.88	1.24	0.88	1.24	
		0.80		0.07	0.50	0.07	0.50	
		1.10		0.08	0.46	0.08	0.46	- V
.,	V _H Hysteresis Voltage	1.40		0.18	0.56	0.18	0.56	
V _H		1.65		0.27	0.66	0.27	0.66	
	/-	2.30		0.53	0.92	0.53	0.92	
		3.00		0.79	1.31	0.79	1.31	1
		$0.80 \le V_{CC} \le 3.60$	I _{OL} =20 μA		0.10		0.10	
		1.10 ≤ V _{CC} ≤ 1.30			0.30 x V _{CC}		0.30 x V _{CC}	
		1.40 ≤ V _{CC} ≤ 1.60	I _{OL} =1.7 mA		0.31		0.37	
V_{OL}	LOW Level	$1.65 \le V_{CC} \le 1.95$	I _{OL} =1.9 mA		0.31		0.35	V
	Output Voltage	2.30 ≤ V _{CC} ≤ 2.70	I _{OL} =3.1 mA		0.44		0.45	
		2.70 ≤ V _{CC} ≤ 3.60	I _{OL} =4.0 mA		0.44		0.45	
I _{IN}	Input Leakage Current	0V to 3.6 V	$0 \le V_{IN} \le 3.6 V$		±0.1		±0.5	μΑ
I _{OFF}	Power Off Leakage Current	0V	$0 \le (V_{IN}, V_O)$ $\le 3.6 \text{ V}$		0.2		0.6	μA
ΔI_{OFF}	Additional Power Off Leakage Current	0V to 0.2 V	V _{IN} or V _O =0 V to 3.6 V		0.2		0.6	μA
	Quiescent	0.91/ to 2.61/	V _{IN} - V _{CC} or GND		0.5		0.9	
I _{CC}	Supply Current	0.8V to 3.6 V	$V_{CC} \le V_{IN} \le 3.6 \text{ V}$				±0.9	μΑ
ΔI_{CC}	Increase in I _{CC} per Input	3.3 V	V _{IN} =V _{CC} -0.6 V		40.0		50.0	μA

AC Electrical Characteristics

Complete Bonomet		400 V	Complition	T _A =25°C			T _A =-40 to 85°C		I Imia
Symbol Par	Parameter	V _{cc}	Condition	Min.	Тур.	Max.	Min.	Max.	Unit
		0.80			30				
		$1.10 \le V_{CC} \le 1.30$	C -15 pE	1.0	10.1	18.9	1.0	19.9	
	Propagation	$1.40 \le V_{CC} \le 1.60$	$C_L=15 \text{ pF},$ $R_U=R_D=5 \text{ K}\Omega$	1.0	6.6	11.4	1.0	12.2	
t_{PZL}, t_{PLZ}	Delay	$1.65 \le V_{CC} \le 1.95$	$V_I = 2 \times (V_{CC})$	1.0	6.3	8.7	1.0	9.7	
		$2.30 \le V_{CC} \le 2.70$	(see Figure 9)	1.0	4.7	6.9	1.0	7.5	
		$3.00 \le V_{CC} \le 3.60$		1.0	4.6	6.8	1.0	7.4	
C _{IN}	Input Capacitance	0			0.8				pF
C _{OUT}	Output Capacitance	0			1.7				pF
	//	0.80			3.0				
		$1.10 \le V_{CC} \le 1.30$			3.1				
0	Power	$1.40 \le V_{CC} \le 1.60$	V _{IN} =0V or V _{CC} ,		3.2				
C_{PD}	Dissipation Capacitance	$1.65 \le V_{CC} \le 1.95$	f=10 MHz		3.4				pF
		$2.30 \le V_{CC} \le 2.70$			3.8				
		$3.00 \le V_{CC} \le 3.60$			4.4				

AC Loadings and Waveforms



Notes:

- $C_{\rm L}$ includes load and stray capacitance. Input PRR = 1.0 MHz, $t_{\rm W}$ = 500 ns.

Figure 9. **AC Test Circuit**

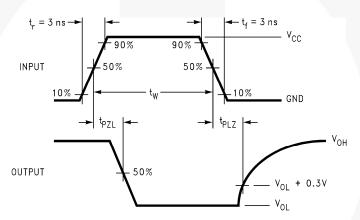
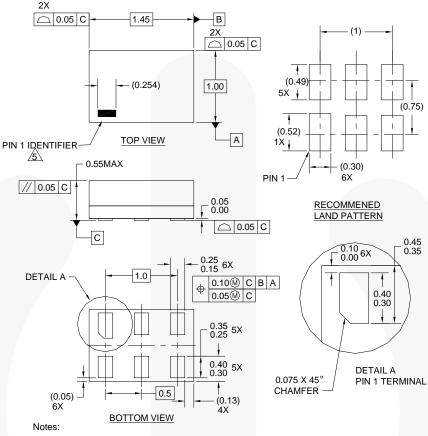


Figure 10. AC Waveforms

Symbol		V _{cc}				
Symbol	3.3 V ± 0.3 V	2.5 V ± 0.2 V	1.8 V ± 0.15 V	1.5 V ± 0.10 V	1.2 V ± 0.10 V	V 8.0
V _{mi}	V _{cc} /2	V _{CC} /2	V _{CC} /2	V _{CC} /2	V _{CC} /2	V _{CC} /2
V _X	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V	V _{OL} + 0.1 V	V _{OL} + 0.1 V	V _{OL} + 0.1 V

Physical Dimensions



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994
- 4. FILENAME AND REVISION: MAC06AREV4
- OTHER LINE IN THE MARK CODE LAYOUT.

Figure 11. 6-Lead MicroPak™ 1.0 x 1.45 mm, JEDEC MO-252

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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

Physical Dimensions

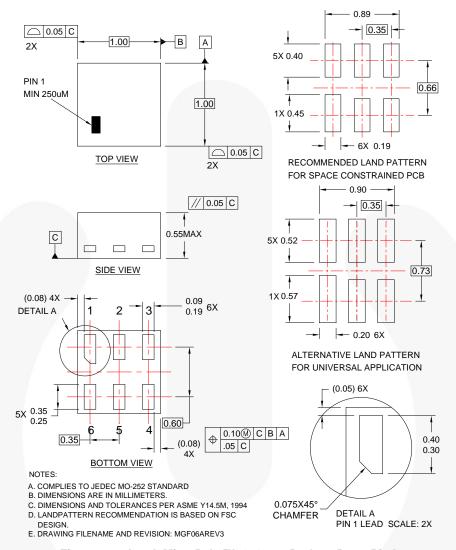


Figure 12.6-Lead, MicroPak2™, 1x1 mm Body, .35 mm Pitch

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Tape and Reel Specifications

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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed





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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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